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a tip end to be brought into contact with said external connection terminal;
resiliently-deformable bulging sections which extend horizontally with respect to
said tip end; and
a terminal for insertion into a circuit board.

7. (Amended) The method of manufacturing the contact of the test socket
defined in claim 6, comprising the steps of:

punching material so as to define the profile of a contact of a test socket belonging
to an electronic device or semiconductor package;

forming, in a tip end to be brought into contact with an external connection terminal
of a member to be tested of the punched component, a plurality of protuberances and a
plurality of recesses from smoothly-curved surfaces such that the recesses are located
adjacent to the protuberances; and

forming a film on the punched component having the irregularities formed therein.

8. (Amended) The test method involving use of the contact of the test socket
as defined in claim 1, comprising the steps of:

bringing an external connection terminal of a member to be tested into contact with
a tip end of the contact of the test socket;

sending, to the member, an electric signal transmitted from a terminal connected to
a circuit board; and

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testing the operation of the member through use of the electric signal returned from
the test member.

10. (Amended) A test socket comprising:

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a test board;

a seat for a member to be tested; and

a contact to be electrically connected to an external connection terminal of the
member to be tested and is to be used for testing the electrical characteristic of the
member, wherein

said contact includes:

a plurality of tip ends to be brought into contact with each other when brought into
contact with the external connection terminal;

resilient sections connected to said respective tip ends; and

a support section to which said resilient sections are connected or to which one
resilient section is connected by way of the other resilient section.

17. (Amended) A method of manufacturing said contact of said test socket
defined in claim 10, comprising the steps of:

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punching a member having the property of a spring into a component so as to define
the profile of a contact of a test socket belonging to an electronic device or semiconductor
package;

splitting a tip end of the contact into a plurality of pieces; and

~~plating said punched component.~~

18. (Amended) A method of manufacturing said contact of said test socket defined in claim 16, comprising the steps of:

~~punching a member having the property of a spring into a component so as to define the profile of a contact of a test socket belonging to an electronic device or semiconductor package;~~

~~splitting a tip end of the contact into a plurality of pieces;~~

~~forming a plurality of protuberances and recesses from smooth surfaces in the surfaces of the tip end such tat the protuberances and recesses are adjacent to each other;~~

~~plating the roughened component.~~

19. (Amended) A test method involving use of the contact of the test socket as defined in claim 10, comprising the steps of:

~~bringing an external connection terminal of a member to be tested into contact with a tip end of the contact of said test socket;~~

~~sending, to said member, an electric signal transmitted from a terminal connected to a circuit board; and~~

~~testing the operation of the member through use of the electric signal returned from the test member.~~